

Title (en)
SENSOR SYSTEM COMPRISING A CERAMIC HOUSING

Title (de)
SENSORSYSTEM MIT KERAMISCHEM GEHÄUSE

Title (fr)
SYSTÈME DE CAPTEUR COMPORTANT UN BOÎTIER CÉRAMIQUE

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Application
EP 13799504 A 20131120

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Abstract (en)
[origin: WO2014127861A1] The invention relates to a sensor system comprising a sensor chip (1) which is mounted on a mounting seat (20) of a ceramic housing body (2). The housing body (2) has a three-dimensional, monolithic design and is produced from a ceramic material with a thermal expansion coefficient which, in a temperature range of greater than or equal to -40°C and less than or equal to 150°C, deviates by less than 30% from the thermal expansion coefficient of the sensor chip (1).

IPC 8 full level
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C-Set (source: EP US)
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EP 2056087 A1 20090506 - PANASONIC ELEC WORKS CO LTD [JP]

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